

NEWS RELEASE

US Conec and SANWA Technologies Announce a Licensing Agreement to Multisource and Develop MDC and MMC Very Small Form Factor (VSFF) Connector Solutions

HICKORY, NC & PLANO, TX, March 24, 2025 – US Conec and SANWA Technologies announce the execution of a definitive license agreement enabling SANWA Technologies to produce and supply MDC VSFF (Very Small Form Factor) duplex optical connectors, MDC VSFF duplex adapters and MMC VSFF multi-fiber adapters. The collaboration to develop and deliver MDC and MMC connectivity solutions ensures a robust supply chain for emerging and future optical link architectures.

Next-generation link architectures employing 800G and beyond with state-of-the-art pluggable transceivers and embedded optic solutions are demanding higher-density fiber-optic cabling solutions that cannot be met with existing MPO and LC technologies. US Conec's MMC and MDC connector formats meet those challenges for both carrier and data center performance requirements.

"We are very excited to partner with US Conec on this licensing agreement, enabling us to commercialize our MDC and MMC connectivity solutions," said Aki Ishikawa, COO and CSO of SANWA Technologies. "In collaboration with US Conec and their expertise in the VSFF technologies, SANWA is fully committed to contribute to further enhancing and strengthening both the MDC and the MMC platforms to meet the rapidly growing market demands and application needs."

"It's exciting to have SANWA Technologies on board as a partner for the MMC and MDC connector platforms," said Mike Hughes, VP of Product Management at US Conec. "Their long history of proven connector technology development and superior customer support will help to ensure that market needs related to the proliferation of the VSFF solutions are soundly met."

Very Small Form Factor (VSFF) MDC and MMC Connector Solutions

MDC and MMC
VSFF Connectors



IP5X
Dust Protection
Shuttered Adapters



US Conec and SANWA Technologies will showcase their MDC and MMC solutions at OFC 2025 in San Francisco from April 1-3, 2025. Visit US Conec at Booth #1443 and SANWA at Booth #3126 to learn more.

About SANWA Technologies:

SANWA Technologies is a renowned leading manufacturer of communication equipment servicing the global optical communications market. With over 75 years of innovation and engineering excellence, we continue our rich history of developing and manufacturing quality connectivity solutions and components to enhance the performance of optical networks of today and into the future. SANWA Technologies is headquartered in Tokyo, Japan, with its main production in Thailand and global sales operations in Texas and Massachusetts in the US, as well as Poland and Taiwan. For more information, please visit www.SANWA-tech.com.

About US Conec:

US Conec is a global leader in the design and development of high-density optical interconnects. With over 30 years of innovative experience, the company provides industry leading components for data center and enterprise structured cabling, public networks, circuit board interconnect, and industrial and military markets worldwide. US Conec is headquartered in Hickory, North Carolina, and is an equity venture of three leading communications technology companies—Corning Optical Communications, Fujikura, and NTT-AT. For more information, please visit www.usconec.com.

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